

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (currently amended): A solder deposition method comprising the steps of:

forming a dam ~~around an electrode on a substrate~~ so as to surround electrodes on the surface of a substrate having electrodes in its surface and covered with a solder resist film that is provided with an opening part disposed in the electrodes;

applying a solder precipitating composition to said substrate; and

depositing solder on the surface of said electrode while heating said solder precipitating composition applied.

2. (original): The solder deposition method according to claim 1 wherein said step of forming a dam includes the steps of:

forming a resin film on the surface of said substrate; and

providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

3. (original): The solder deposition method according to claim 1 wherein said dam is not removed after depositing solder.

4. (original): The solder deposition method according to claim 1 wherein said substrate is a via-on-pad structured substrate.

5. (currently amended): The solder deposition method according to claim 1 wherein said solder precipitating composition contains:

a tin powder; and

a complex of at least one selected from the group consisting of silver ions and copper ions, and at least one selected from the group consisting of aryl phosphines, alkyl phosphines and azoles.

6. (currently amended): The solder deposition method according to claim 1 wherein said solder precipitating composition contains a tin powder and a salt of at least one metal selected from the group consisting of lead, copper and silver.

7. (currently amended): A solder bump forming method comprising the steps of:
forming a dam ~~around an electrode on a substrate~~ so as to surround electrodes on the surface of a substrate having electrodes in its surface and covered with a solder resist film that is provided with an opening part disposed in the electrodes;

applying a solder precipitating composition to said substrate; and

forming a solder bump by depositing solder on the surface of said electrode while heating said solder precipitating composition applied.

8. (new): A solder deposition method comprising the steps of:
forming a dam around an electrode on a substrate;
applying a solder precipitating composition to said substrate; and
depositing solder on the surface of said electrode while heating said solder precipitating composition applied,
wherein said solder precipitating composition contains a tin powder; and a complex of at least one selected from the group consisting of silver ions and copper ions, and at least one selected from the group consisting of aryl phosphines, alkyl phosphines and azoles.

9. (new): A solder deposition method comprising the steps of:
forming a dam around an electrode on a substrate;
applying a solder precipitating composition to said substrate; and
depositing solder on the surface of said electrode while heating said solder precipitating composition applied,
wherein said solder precipitating composition contains a tin powder and a salt of at least one metal selected from the group consisting of lead, copper and silver.